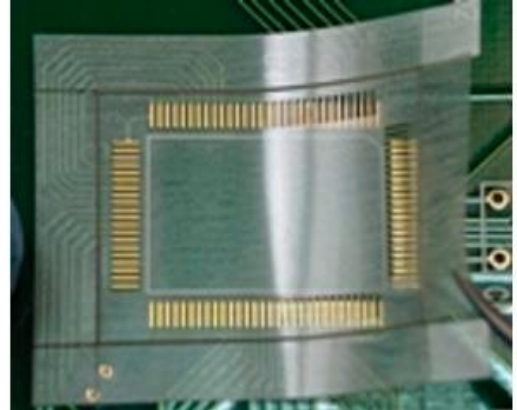


STIKNPEEL™ REWORK STENCILS

DESCRIPTION

StikNPeel™ stencils are made from a custom mylar film with an adhesive backing. It's backside is coated with a "tacky" adhesive and is backed with a release liner. The StikNPeel™ stencils are pre-scored to allow for easy removal from the release liner.



StikNPeel™ stencils are intended for use as a replacement for the metal stencils used in PCB rework. They are intended for temporary attachment to the PCB using a "tacky" temporary adhesive which is used to keep the stencil coplanar with the PCB and prevent leaching of the solder paste underneath the stencil. It's also used to slide around the stencil until the fine adjustments to the board lands are made. The stencils are used to selectively print solder paste and is available in 4, 5 and 6 mil thicknesses.

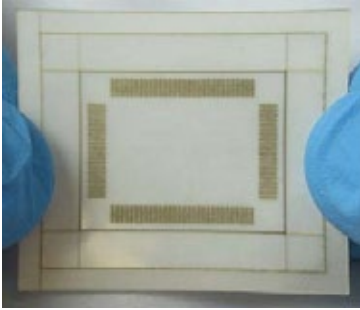
FEATURES

Excellent chemical, and impact resistance. The StikNPeel™ stencils are intended for use as a replacement for the metal stencils used in PCB rework. They are dimensionally stable after being laser machined to the patterns of the PCB lands. It's flexible nature gives it the ability to be used in high-density areas.

SPECIFICATIONS

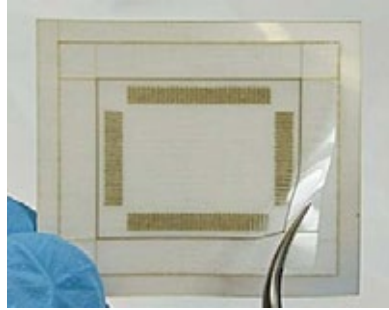
PHYSICAL PROPERTIES			
	Material	Convention Units	S.I. Units
Thickness	Mylar	3.0/4.0/5.0 mils	76/102/127 microns
	Adhesive	1.0 mils	25 microns
	Total	4.0/5.0/6.0 mils	102/127/152 microns
Adhesive Performance	Steel ASTM D3330 180 degree peel, 72 hr dwell	50oz/in	5.4N/100mm
Storage Temperatures	Store in original packaging at 70° F (21° C) and 50% RH.		
Application temperature	Less than 80° F (26.7° C) and 30% RH.		
Elongation	135% at break		
Storage Time	2 Years at the proper storage conditions.		

USER INSTRUCTIONS



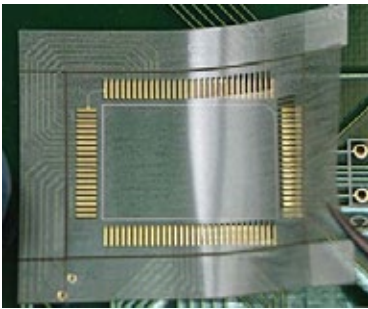
STEP 1

Examine the stencil to make sure that it fits the land patterns on the PCB. Make sure site is wicked (if reworked) and cleaned.



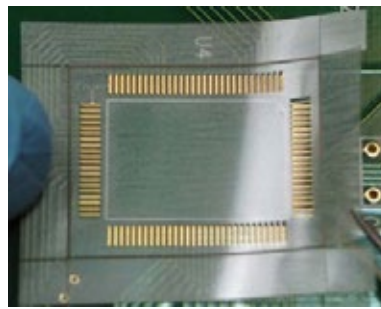
STEP 2

From the corner work the stencil off the backing material.



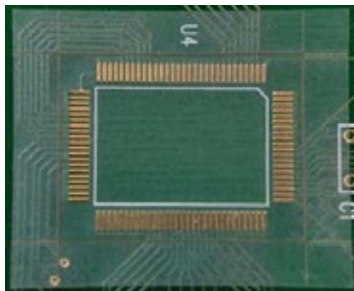
STEP 3

Once the stencil has been peeled off the release liner begin aligning at a corner of the pattern and "work" the alignment slowly in X and Y over the land patterns.



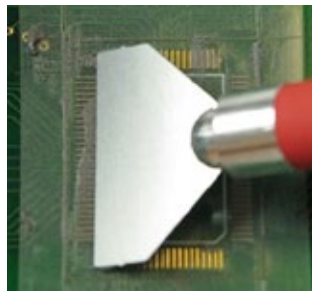
STEP 4

Finish aligning and placing the stencil.



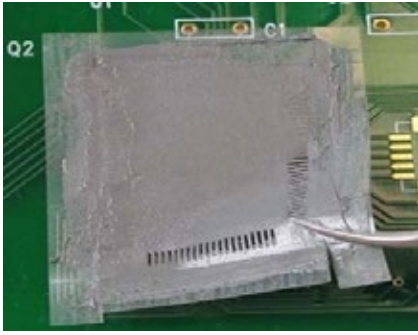
STEP 5

Once aligned and place insure that the hole patterns in the stencil align with the land patterns on the board. Make the board or solder "fence" around the pattern by folding up the sides.



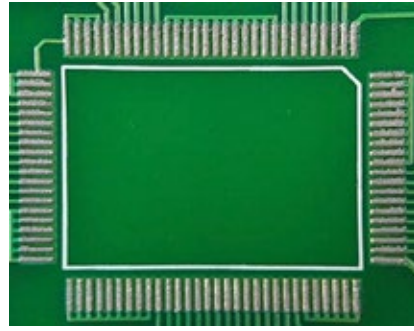
STEP 6

Roll solder paste through the apertures. You can squeegee the paste as many times as you want. Do not press too firmly else the stencil may shift on you.



STEP 7

Pull off the stencil carefully making sure no solder paste is accidentally smeared on neighboring areas of the board/parts. Discard stencil.



STEP 8

Inspect solder paste. You are now ready to place the part.